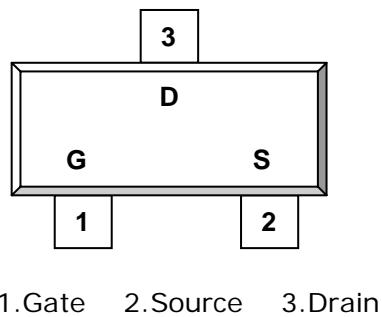


ST2305A

DESCRIPTION

ST2305A is the P-Channel logic enhancement mode power field effect transistor which is produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management, other battery powered circuits, and low in-line power loss are required. The product is in a very small outline surface mount package.

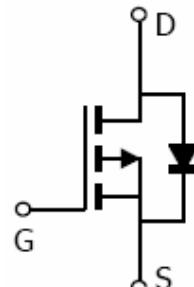
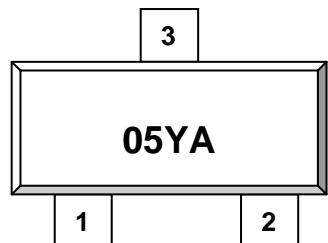
PIN CONFIGURATION SOT-23-3L



FEATURE

- -15V/-3.5A, $R_{DS(ON)} = 45\text{m-ohm}$ (Typ.)
@VGS = -4.5V
- -15V/-3.0A, $R_{DS(ON)} = 55\text{m-ohm}$
@VGS = -2.5V
- -15V/-2.0A, $R_{DS(ON)} = 90\text{m-ohm}$
@VGS = -1.8V
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23-3L package design

PART MARKING SOT-23-3L



ORDERING INFORMATION

Part Number	Package	Part Marking
ST2305AS23RG	SOT-23-3L	05YA

※ Process Code : A ~ Z ; a ~ z

※ ST2305AS23RG S : SOT-23-3L ; R : Tape Reel ; G : Pb – Free

ST2305A

ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	-15	V
Gate-Source Voltage	V _{GSS}	±12	V
Continuous Drain Current TJ=150°C	I _D	-3.5 -2.8	A
Pulsed Drain Current	I _{DM}	-10	A
Continuous Source Current (Diode Conduction)	I _S	-1.6	A
Power Dissipation	P _D	1.25 0.8	W
Operation Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	120	°C/W

ST2305A

ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250uA	-15			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250uA	-0.3		-1.5	V
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V, V _{GS} =0V			-1	uA
		V _{DS} =-20V, V _{GS} =0V T _J =55°C			-10	
On-State Drain Current	I _{D(on)}	V _{DS} ≤-5V, V _{GS} =-4.5V V _{DS} ≤-5V, V _{GS} =-2.5V	-6 -3			A
Drain-source On-Resistance	R _{D(on)}	V _{GS} =-4.5V, I _D =-3.5A V _{GS} =-2.5V, I _D =-2.0A V _{GS} =-1.8V, I _D =-2.0A		0.045 0.055 0.09		Ω
Forward Transconductance	g _{fs}	V _{DS} =-5V, I _D =-3.5V		8.5		S
Diode Forward Voltage	V _{SD}	I _s =-1.6A, V _{GS} =0V		-0.8	-1.2	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =-10V V _{GS} =-4.5V I _D ≡-3.5A		10	12	nC
Gate-Source Charge	Q _{gs}			2		
Gate-Drain Charge	Q _{gd}			2		
Input Capacitance	C _{iss}	V _{DS} =-10V V _{GS} =0V F=1MHz		485		pF
Output Capacitance	C _{oss}			90		
Reverse Transfer Capacitance	C _{rss}			40		
Turn-On Time	t _{d(on)} tr	V _{DD} =-10V R _L =6Ω I _D =-1.0A V _{GEN} =-4.5V R _G =6Ω		10	18	nS
Turn-Off Time	t _{d(off)} tf			13	22	
				18	24	
				15	20	